## REMARKS

Claims 1-10 were pending in the application. The Examiner has rejected claims 1-10 under 35 U.S.C. §103(a) as being unpatentable over Hamburgen et al. (U.S. Patent No. 5,582,242, hereafter "Hamburgen") in view of Luo (U.S. Patent No. 6,725,909, hereafter "Luo").

Based on the discussions in the August 23, 2005 interview, Applicant further amends claim 1 to provide a more precise descriptions in detail. The amendment doesn't include any new matter.

Hambergen discloses a method avoid trapping solder fluxes or additional materials in the thermosiphon. Hambergen employs an intrinsically clean sealing technique, where the copper tube of the condenser 28 is hermetically sealed onto the boiler 26 by a shape memory ring 34A, or shrink ring. The shrinking squeezes the condenser 28 on to a small protruding region, or sealing land 27 on the outside diameter of the boiler 26. (See Hambergen at column 4, lines 49 – 60 and Figs 1 and 2). While Luo discloses a heat dissipating device and method for fabricating such device. Luo discloses a cover used in the heat dissipating device (see figures 2 and 13, column 4, lines 45 – 55).

Nevertheless. Applicant respectfully submits that the amended claim 1 and it dependent claims having elements that is not taught, suggested within the cited prior art or their combination.

If the Examiner believes that a further telephonic interview will facilitate allowance of the claims, he is respectfully requested to contact the undersigned at (610) 446-5886. For the reasons stated above, Applicants respectfully assert that the pending claims are in condition for allowance. Reconsideration and allowance of the pending claims are respectfully requested.

## Respectfully submitted,

Respectfully submitted,

HDLS

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11/02/2005 07:45

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Date: November 2, 2005

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the PATENT APPLICATION of:

Hul-Chun Hsu

Application No.:

10/799 655

Filed:

March 15, 2004

For:

END SURFACE STRUCTURE OF THE HEAT

PIPE

Group:

3743

Examiner:

McKirmon, Terrell L.

REPLY PURSUANT TO 37 C.F.R. §1.116

Commissioner for Patents PO Box 1450

Alexandria, VA 22313-1450

Six:

It is respectfully requested that the period for replying to the Final Office Action dated July 28, 2005 be extended for one month under the provisions of 37 C.F.R. 1.136(a).

Please charge the applicable extension fee of \$60.00 pursuant to 37 C.F.R. 1.17(a) to the Deposit Account, No. 503303

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